

FIGURE 1: PRINCIPAL DIMENSIONS AND DATUMS

JEDEC SOLID STATE PRODUCT OUTLINE	.050 CENTER NON-HERMETIC LEADLESS CHIP CARRIER QUAD SERIES	ISSUE A	DATE 12-87	MO-075	SHEET 1 OF 5
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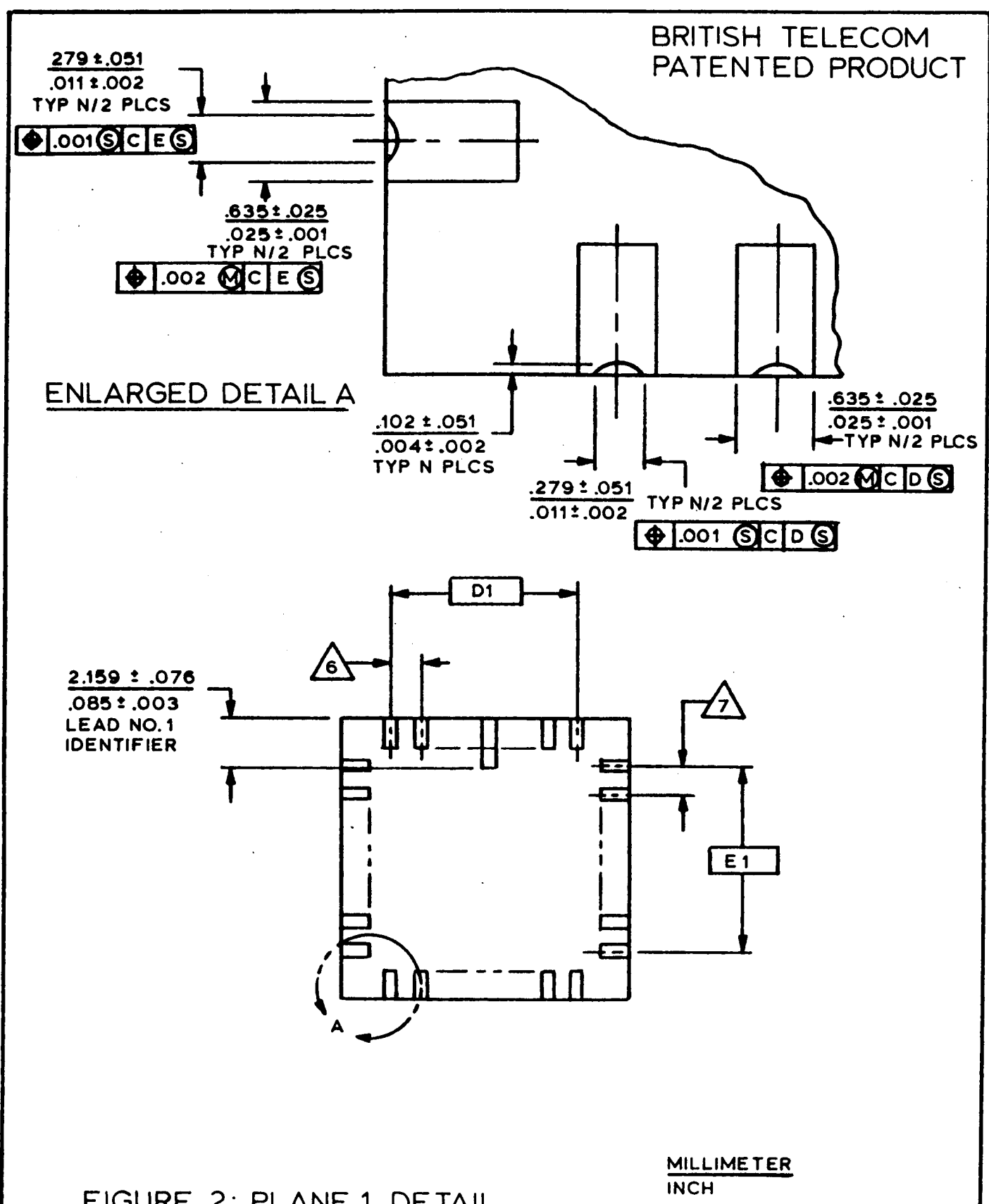


FIGURE 2: PLANE 1 DETAIL

JEDEC SOLID STATE PRODUCT OUTLINE	.050 CENTER NON-HERMETIC LEADLESS CHIP CARRIER QUAD SERIES	ISSUE A	DATE 12/87	MO-075	SHEET 2 OF 5
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S Y M B O L	VARIATIONS ALL DIMENSIONS IN INCHES											
	AA		N O T E	AB		N O T E	AC		N O T E			N O T E
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX	
D	.348	.352		.398	.402		.448	.452				
D1	.200	BASIC	6	.200	BASIC	6	.200	BASIC	6			
D2	.340	REF		.384	REF		.440	REF				
E	.348	.352		.398	.402		.448	.452				
E1	.200	BASIC	7	.250	BASIC	7	.300	BASIC	7			
E2	.340	REF		.384	REF		.440	REF				
e	.050	BASIC	6,7	.050	BASIC	6,7	.050	BASIC	6,7			
M	.5		6,7	6		6,7	7		6,7			
N	20		4	24		4	28		4			

S Y M B O L	VARIATIONS ALL DIMENSIONS IN MILLIMETERS													
	AA		N O T E	AB		N O T E	AC		N O T E			N O T E		
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX			
D	8.840	8.940		10.109	10.211		11.380	11.480						
D1	5.080	BASIC	6	6.350	BASIC	6	7.620	BASIC	6					
D2	8.636	REF		9.754	REF		11.176	REF						
E	8.840	8.940		10.109	10.211		11.380	11.480						
E1	5.080	BASIC	7	6.350	BASIC	7	7.620	BASIC	7					
E2	8.636	REF		9.754	REF		11.176	REF						
e	1.270	BASIC	6,7	1.270	BASIC	6,7	1.270	BASIC	6,7					
M	5		6,7	6		6,7	7		6,7					
N	20		4	24		4	28		4					
NOTE	1, 2, 3, 5			1, 2, 3, 5			1, 2, 3, 5							
REF	Item 11-221													
ISSUE	A													
JEDEC SOLID STATE PRODUCT OUTLINE			.050 CENTER NON-HERMETIC LEADLESS CHIP CARRIER QUAD SERIES				ISSUE A		DATE 12/87		MO-075		SHEET 3 of 5	

S Y M B O L	VARIATIONS ALL DIMENSIONS IN INCHES											
	AD		N O T E	AE		N O T E	AF		N O T E			N O T E
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX	
D	.648	.652		.948	.952		1.148	1.152				
D1	.500	BASIC	6	.800	BASIC	6	1.000	BASIC	6			
D2	.640	REF		.940	REF		1.140	REF				
E	.648	.652		.948	.952		1.148	1.152				
E1	.500	BASIC	7	.800	BASIC	7	1.000	BASIC	7			
E2	.640	REF		.940	REF		1.140	REF				
e	.050	BASIC	6,7	.050	BASIC	6,7	.050	BASIC	6,7			
M	11		6,7	17		6,7	21		6,7			
N	44		4	68		4	84		4			

S Y M B O L	VARIATIONS ALL DIMENSIONS IN MILLIMETERS													
	AD		N O T E	AE		N O T E	AF		N O T E			N O T E		
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX			
D	16.460	16.560		24.080	24.180		29.160	29.260						
D1	12.700	BASIC	6	20.320	BASIC	6	25.400	BASIC	6					
D2	16.256	REF		23.876	REF		28.956	REF						
E	16.460	16.560		24.080	24.180		29.160	29.260						
E1	12.700	BASIC	7	20.320	BASIC	7	25.400	BASIC	7					
E2	16.256	REF		23.876	REF		28.956	REF						
e	1.270	BASIC	6,7	1.270	BASIC	6,7	1.270	BASIC	6,7					
M	11		6,7	17		6,7	21		6,7					
N	44		4	68		4	84		4					
NOTE	1, 2, 3, 5			1, 2, 3, 5			1, 2, 3, 5							
REF	Item 11-221													
ISSUE	A													
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NOTES:

1. REFER TO APPLICABLE SYMBOL LIST.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M 1982.
3. CONTROLLING DIMENSION: INCH.
4. N IS THE MAXIMUM QUANTITY OF TERMINAL POSITIONS.
5. PACKAGE SHALL BE FREE OF BURRS AND CORNERS SHALL BE SMOOTH.
6. M CENTERLINES SPACED AT e EQUAL TO $D1$.
7. M CENTERLINES SPACED AT e EQUAL TO $E1$.
8. FEATURES FOR ELECTRICAL/OPTICAL ORIENTATION OR HANDLING PURPOSES MUST BE WITHIN THE AREA SHOWN.
9. THE LID DEFINED BY D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.
10. THIS TECHNOLOGY WAS DEVELOPED IN THE U.K. FOR BRITISH TELECOMMUNICATIONS WHO HAVE PATENTS AND/OR PATENTS PENDING WORLD-WIDE. PRODUCTS EMPLOYING THE TECHNOLOGY ARE PRESENTLY MANUFACTURED BY TECTONIC PRODUCTS LTD. OF WOKINGHAM, U.K. THROUGH WHOM LICENSING IS AVAILABLE IN COMPLIANCE WITH PARAGRAPH 3.4 b) OF EIA ENGINEERING PUBLICATION EP-7-A.